

# Specification Sheet

## Silicon Wafer Platinum Coated

(Pt/TaOx on SiO<sub>2</sub>/Si wafer)

Stock No: NS6130-10-1152, CAS: 7440-21-3

<b>Product</b>	:	<b>Silicon Wafer Platinum Coated</b>
Stock No	:	NS6130-10-1152
CAS	:	7440-21-3
Structure	:	Pt/TaOx on SiO <sub>2</sub> /Si wafer (4 inch)
Film	:	Pt/TaOx (Platinum on Tantalum Oxide)
Orientation of Film	:	(111)
Thickness of PT Film	:	200nm (Sputtering method)
Thickness of TaOx Film	:	40nm (Sputtering method)
Substrate	:	SiO <sub>2</sub> /Si Wafer
Thickness of SiO <sub>2</sub>	:	300nm (Thermal Oxidation)
Silicon Wafer	:	Single Side Polished
Diameter	:	4" (100mm)
Thickness of Si	:	525 ± 20μm
Crystal Orientation	:	< 100>
Type	:	P (Boron Doped)
Growth Method	:	CZ Prime
Resistivity	:	1 ~ 10 Ω.cm
<b>Main Inspect Verifier</b>	:	<b>Manager QC</b>

**Note:** Product Specification are subject to amendment and may change over time

## Characterization of Silicon Wafer Platinum Coated



Silicon Wafer P Type



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